

具有 3 态输出的 8 透明 D 类锁存器

查询样品: [SN54HC373-DIE](#)

特性

- 宽运行电压范围
- 高电流 3 态真输出可驱动高达 15 个低功耗肖特基晶体管晶体管逻辑 (LSTTL) 负载
- 低功耗
- t_{pd} 典型值 = 13ns
- 低输入电流
- 针对负载的完全并行访问

说明

此 8 位锁存器特有专门设计用于驱动高电容或相对低阻抗负载的 3 态输出。它特别适合于执行缓冲寄存器, I/O 端口, 双向总线驱动器和工作寄存器。

SN54HC373-DIE 的 8 个锁存是透明 D 类型锁存器。在锁存使能 (LE) 输入为高电平时, Q 输出将跟随数据 (D) 输出。当 LE 为低电平时, Q 输出被锁存在 D 输入上设置的电平上。

ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE DESIGNATOR	PACKAGE	ORDERABLE PART NUMBER	PACKAGE QUANTITY
SN54HC373V	TD	Bare die in waffle pack ⁽²⁾	SN54HC373VTDG1	100
			SN54HC373VTDG2	10

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Processing is per the Texas Instruments space production baseline and is in compliance with the Texas Instruments Quality Control System in effect at the time of manufacture. Electrical screening consists of DC parametric and functional testing at room temperature only. Unless otherwise specified by Texas Instruments AC performance and performance over temperature is not warranted. Visual inspection is performed in accordance with MIL-STD-883 Test Method 2010 Condition B at 75X minimum.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BOND PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
10.5 mils.	Silicon with backgrind	Floating	AlCu(2%) TiW	1199 nm

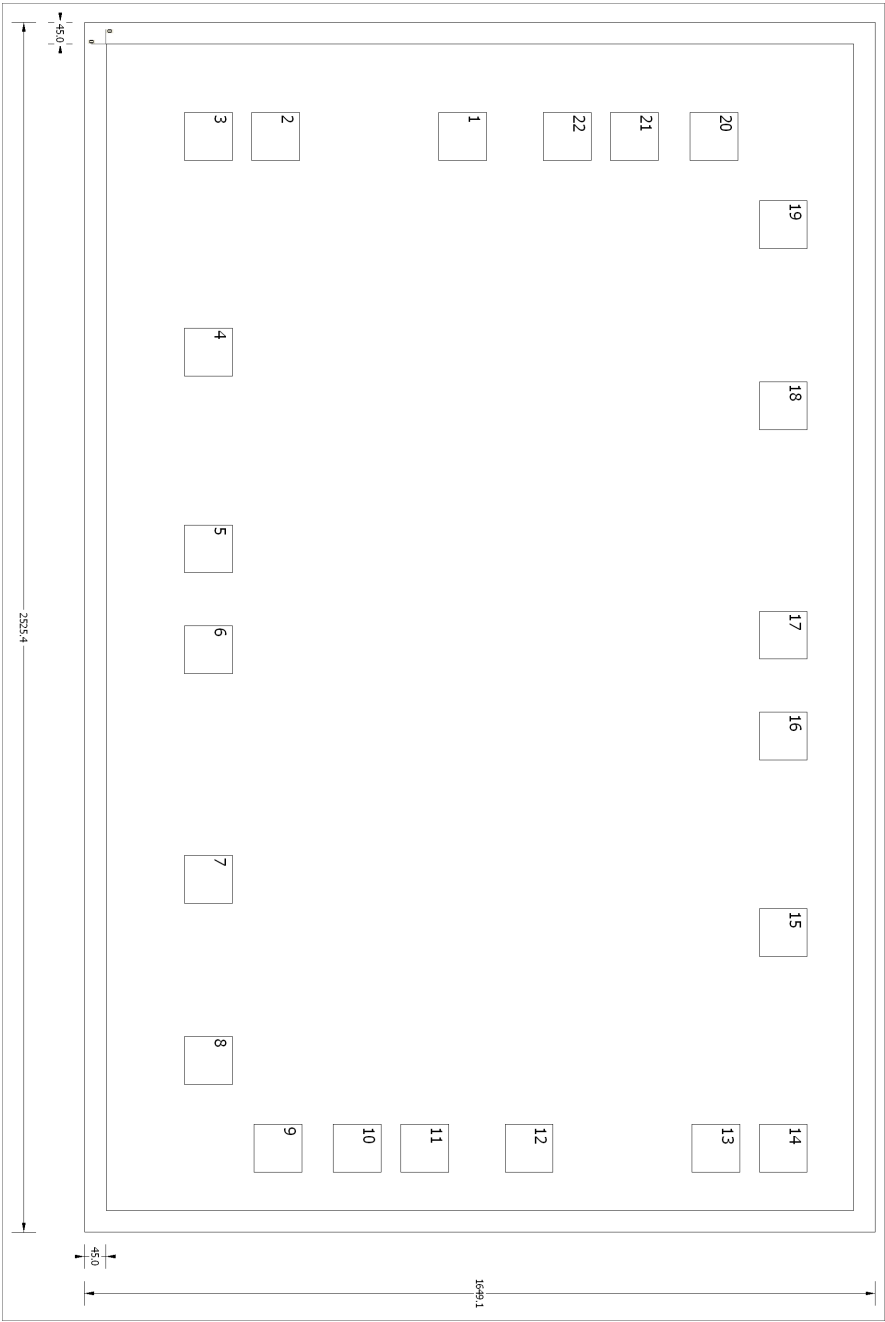


Table 1. Bond Pad Coordinates in Microns

DESCRIPTION	PAD NUMBER	X MIN	Y MIN	X MAX	Y MAX
OE	1	143.1	693	243.9	793.8
1Q	2	143.1	303.3	243.9	404.1
1D	3	143.1	162.9	243.9	263.7
2D	4	593.1	162.9	693.9	263.7
2Q	5	1003.5	162.9	1104.3	263.7
3Q	6	1214.1	162.9	1314.9	263.7
3D	7	1692.9	162.9	1793.7	263.7
4D	8	2070.9	162.9	2171.7	263.7
4Q	9	2254.5	307.8	2355.3	408.6
GND	10	2254.5	473.4	2355.3	574.2
GND	11	2254.5	613.8	2355.3	714.6
LE	12	2254.5	831.6	2355.3	932.4
5Q	13	2254.5	1221.3	2355.3	1322.1
5D	14	2254.5	1361.7	2355.3	1462.5
6D	15	1804.5	1361.7	1905.3	1462.5
6Q	16	1394.1	1361.7	1494.9	1462.5
7Q	17	1183.5	1361.7	1284.3	1462.5
7D	18	704.7	1361.7	805.5	1462.5
8D	19	326.7	1361.7	427.5	1462.5
8Q	20	143.1	1216.8	243.9	1317.6
VCC	21	143.1	1051.2	243.9	1152
VCC	22	143.1	910.8	243.9	1011.6

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN54HC373VTDG1	Active	Production	null (null) 0	100 TUBE	Yes	Call TI	N/A for Pkg Type	25 to 25	
SN54HC373VTDG1.A	Active	Production	null (null) 0	100 TUBE	Yes	Call TI	N/A for Pkg Type	25 to 25	
SN54HC373VTDG2	Active	Production	null (null) 0	10 TUBE	Yes	Call TI	N/A for Pkg Type	25 to 25	
SN54HC373VTDG2.A	Active	Production	null (null) 0	10 TUBE	Yes	Call TI	N/A for Pkg Type	25 to 25	

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54HC373-DIE :

- Space : [SN54HC373-SP](#)

NOTE: Qualified Version Definitions:

- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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